



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-05-26
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Emilio Castelli	<b>Representative Title</b>	APG MD CHAMPION
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TDA7303TR	J5LR*A061CA6	A	MU1A	2014-05-26
Amount	UoM	Unit type	ST ECOPACK Grade	
786.60	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	7.5X18X2.5	28	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	JSLR*A061CA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	6.520	mg	supplier	die	Silicon (Si)	7440-21-3		6.464	mg	991411	8218
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.017	mg	2607	22
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.017	mg	2607	22
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.012	mg	1840	15
die (s)				supplier	passivation	Indium Tin oxide ( In2O3.SnO2 )	50926-11-9		0.010	mg	1534	13
Leadframe	Copper & its alloys	235.187	mg	supplier	alloy	Copper (Cu)	7440-50-8		229.190	mg	974501	291368
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		5.390	mg	22918	6852
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.325	mg	1382	413
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.282	mg	1199	359
Die attach		1.510	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		1.163	mg	770199	1479
Die attach				supplier	glue or tape	Epoxy Cresol Novolak	29690-82-2		0.341	mg	225828	434
Die attach				supplier	glue or tape	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.006	mg	3974	8
Bonding wire		0.965		supplier	wire	Gold (Au)	7440-57-5		0.965	mg	100000	1227
encapsulation		542.418	mg	supplier	mold compound	Silica, vitreous	60676-86-0		433.935	mg	800001	551659
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		37.969	mg	70000	48270
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		21.697	mg	40001	27583
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		32.545	mg	60000	41374
encapsulation				JIG Table B	mold compound	Antimony Trioxide	1309-64-4		6.509	mg	12000	8275
encapsulation				JIG Table B	mold compound	Brominated Epoxy Resin	40039-93-8		8.136	mg	15000	10343
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		1.627	mg	3000	2068